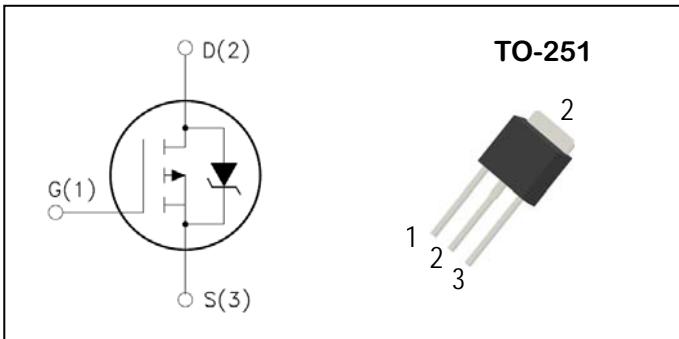


P-Channel Logic Level Enhancement Mode Field Effect Transistor**PRODUCT SUMMARY**

V_{DSS}	I_D	$R_{DS(ON)}$ ($m\Omega$)
-60V	-15A	90m Ω

**Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise specified)**

Symbol	Parameter	Ratings	Unit
Common Ratings			
V_{DSS}	Drain-Source Voltage	-60	V
V_{GSS}	Gate-Source Voltage	± 20	
T_J	Maximum Junction Temperature	150	$^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
I_S	Diode Continuous Forward Current	TC=25°C -15	A
Mounted on Large Heat Sink			
I_{DM}	300 μ s Pulse Drain Current Tested(1)	TC=25°C -50	A
I_D	Continuous Drain Current	TC=25°C -15	A
		TC=100°C -10	A
P_D	Maximum Power Dissipation	TC=25°C 41	W
		TC=100°C 16	W

Thermal Characteristics

Symbol	Parameter	Ratings	Unit
R_{thJC}	Thermal resistance junction-case max	3	$^\circ C/W$
R_{thJA}	Thermal resistance junction-ambient max	120	$^\circ C/W$

1. Pulse width limited by maximum junction temperature.

Electrical Characteristics (TA=25°C Unless Otherwise Noted)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
On/off Characteristics						
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250uA	-60	--	--	V
Idss	Zero Gate Voltage Drain Current	V _{DS} = -48V, V _{GS} =0V	--	--	1	uA
		V _{DS} =-40V, V _{GS} =0V T _J =125°C	--	--	10	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250uA	-1	-1.7	-3	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±250	nA
R _{DSON}	Drain-SourceOn-stateResistance ⁽²⁾	V _{GS} = -10V, I _{DS} =-7A	--	42	55	mΩ
		V _{GS} = -4.5V, I _{DS} =-6A	--	100	135	
g _{FS}	Forward transconductance ⁽²⁾	V _{DS} =- 10V, I _{DS} =-7A	--	9	--	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} = -25V, Frequency=1.0MHz	--	1130	--	pF
C _{oss}	Output Capacitance		--	122	--	
C _{rss}	Reverse Transfer Capacitance		--	75	--	
Switching Characteristics						
t _{d(ON)}	Turn-on Delay Time ⁽¹⁾	V _{DS} =-20V, I _D = -1A, V _{GS} = -10V, R _{GEN} =6 Ω	--	7	--	ns
t _r	Turn-on Rise Time ⁽¹⁾		--	10	--	
t _{d(OFF)}	Turn-off Delay Time ⁽¹⁾		--	19	--	
t _f	Turn-off Fall Time ⁽¹⁾		--	12	--	
Q _g	Total Gate Charge ⁽¹⁾	V _{DS} =0.5V, V _{GS} = -10V, I _{DS} =-7A	--	12.5	--	nC
Q _{gs}	Gate-Source Charge ⁽¹⁾		--	1.8	--	
Q _{gd}	Gate-Drain Charge ⁽¹⁾		--	3.7	--	
Diode Characteristics						
V _{SD}	Diode Forward Voltage ⁽²⁾	I _{SD} = -7A, V _{GS} = 0	--	--	-1	V
t _{rr}	Reverse Recovery Time	I _{SD} =-7A, dI _{SD} /dt=100A/μs	--	37	--	ns
q _{rr}	Reverse Recovery Charge		--	53	--	nC

NOTES:

1. Independent of operating temperature.
2. Pulse Test : Pulse width ≤ 300 μ s, Duty cycle ≤ 2%

Typical Performance Characteristics

Figure 1: On-Region Characteristics

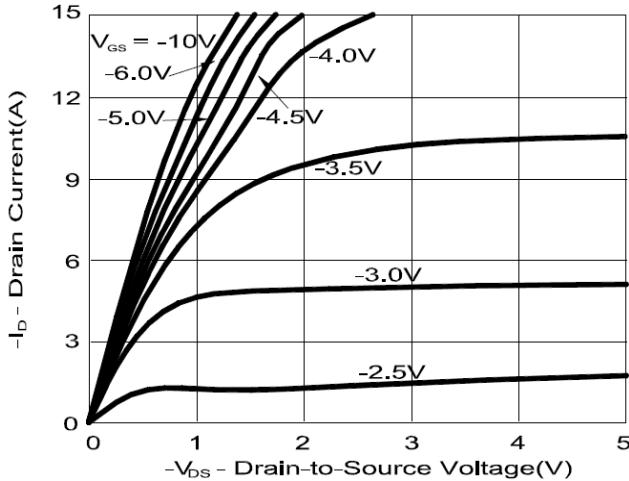


Figure 2: Transfer Characteristics

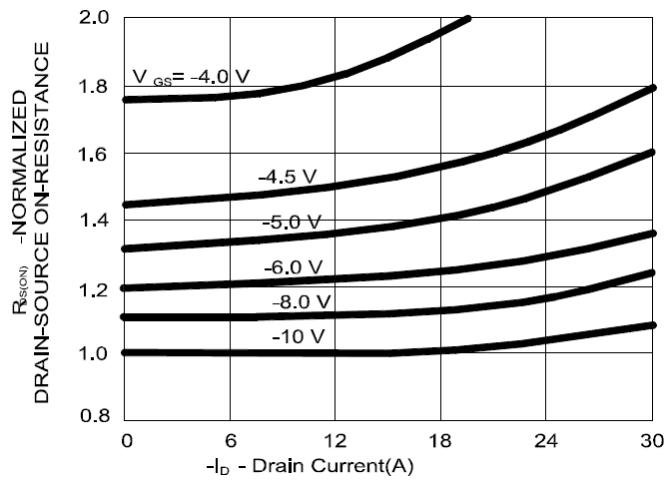


Figure 3: Transfer Characteristics

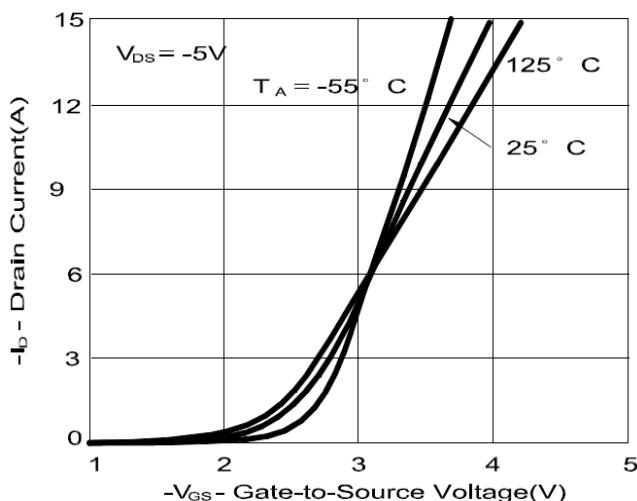


Figure 4: On-Resistance with Gate-to-source Voltage

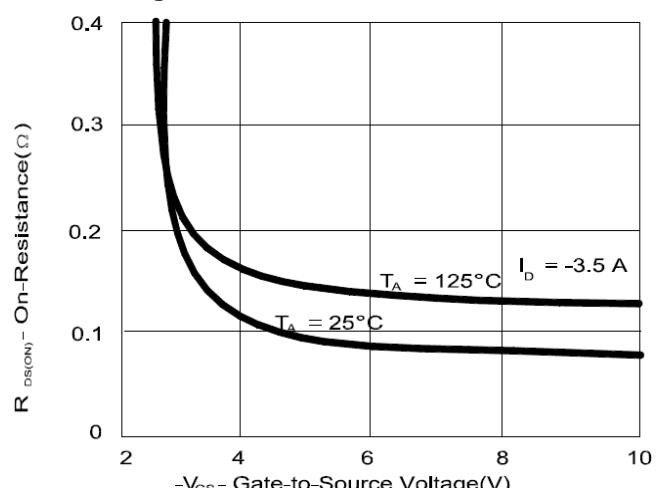


Figure 5: Capacitance Characteristics

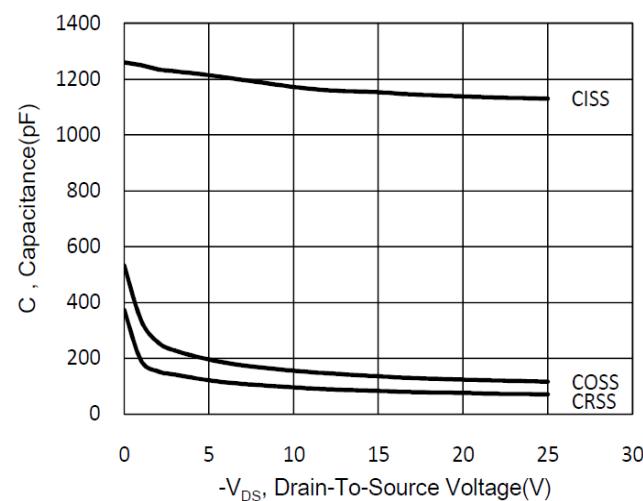


Figure 6: Gate Charge Characteristics

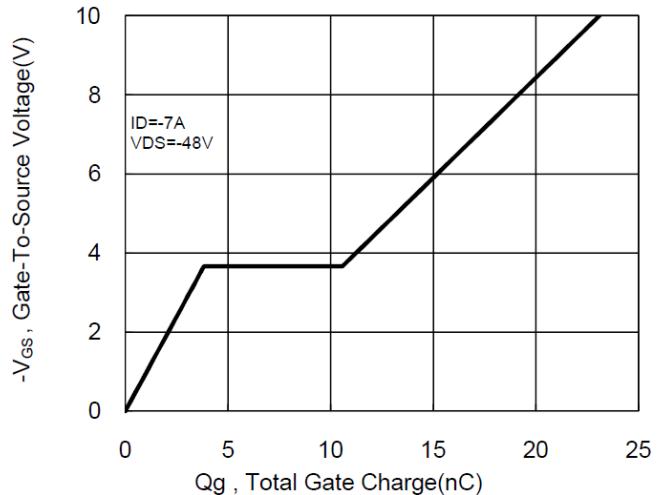
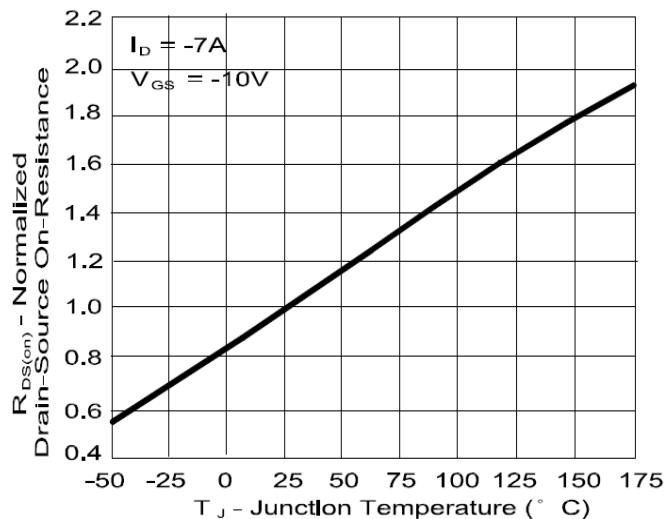
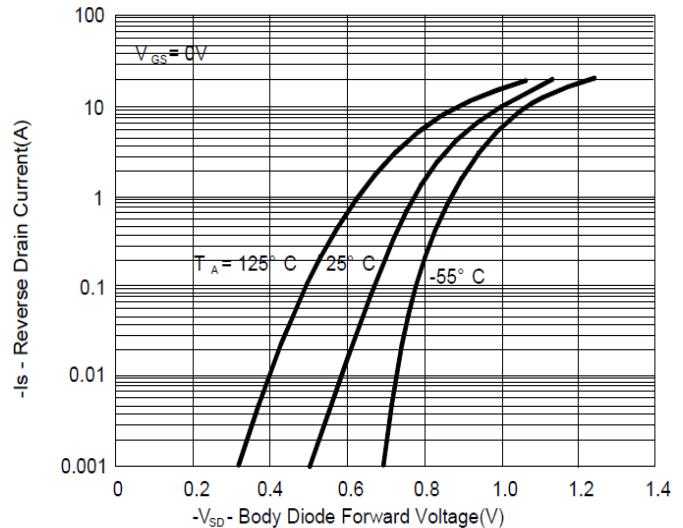
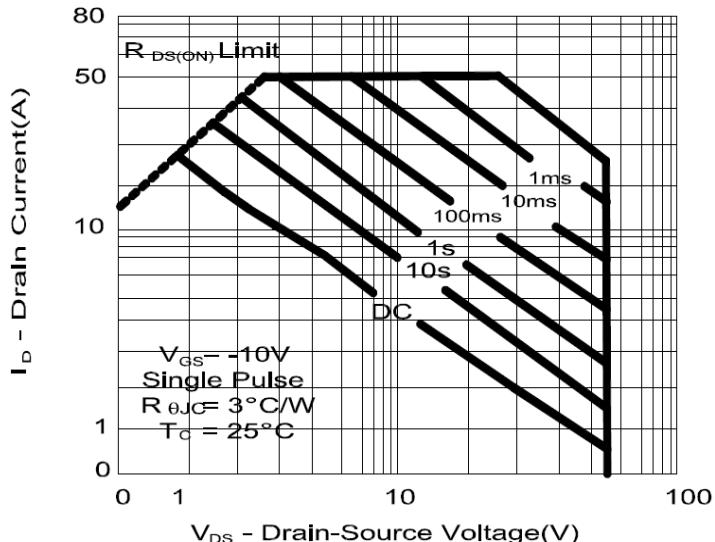
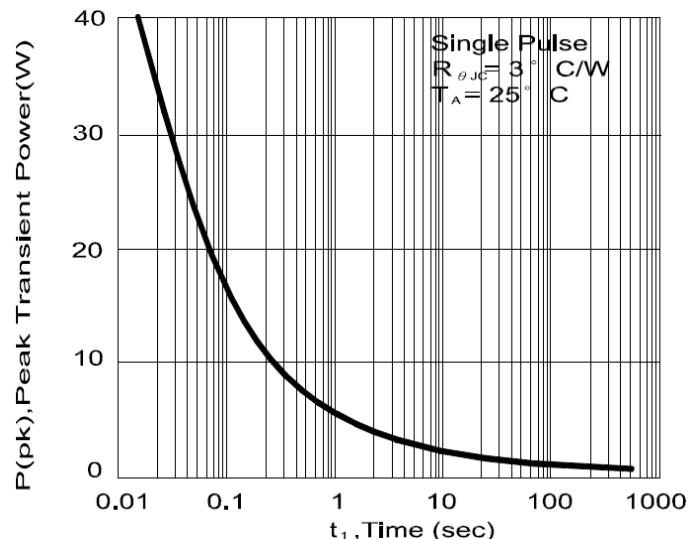
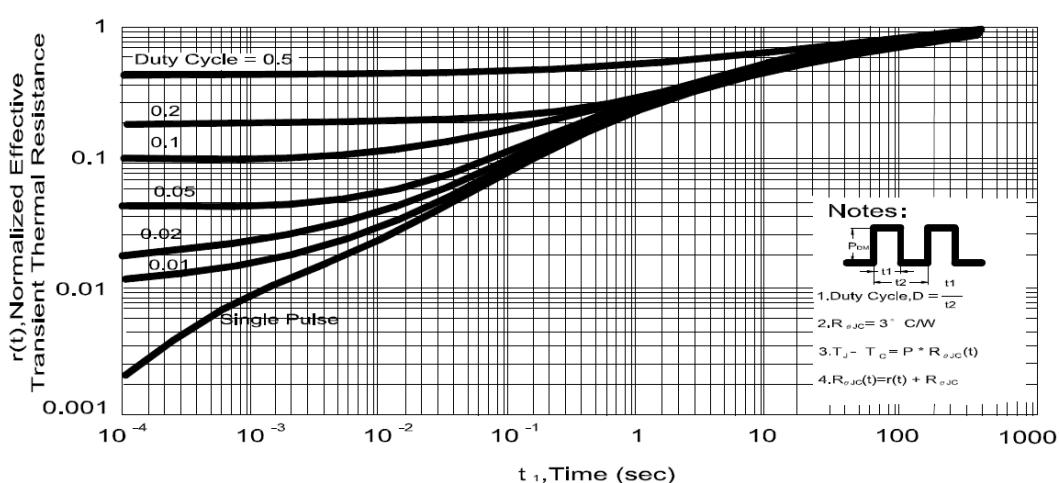
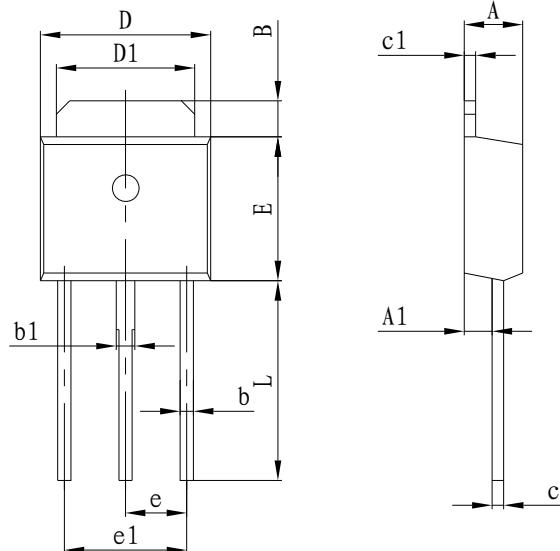


Figure 7: On-Resistance Variation vs.Temperature**Figure 8: Body Diode Forward Voltage****Figure 9: Maximum Safe Operating Area****Figure 10: Pulse Maximum Power Dissipation****Figure 11. Transient Thermal Response Curve**

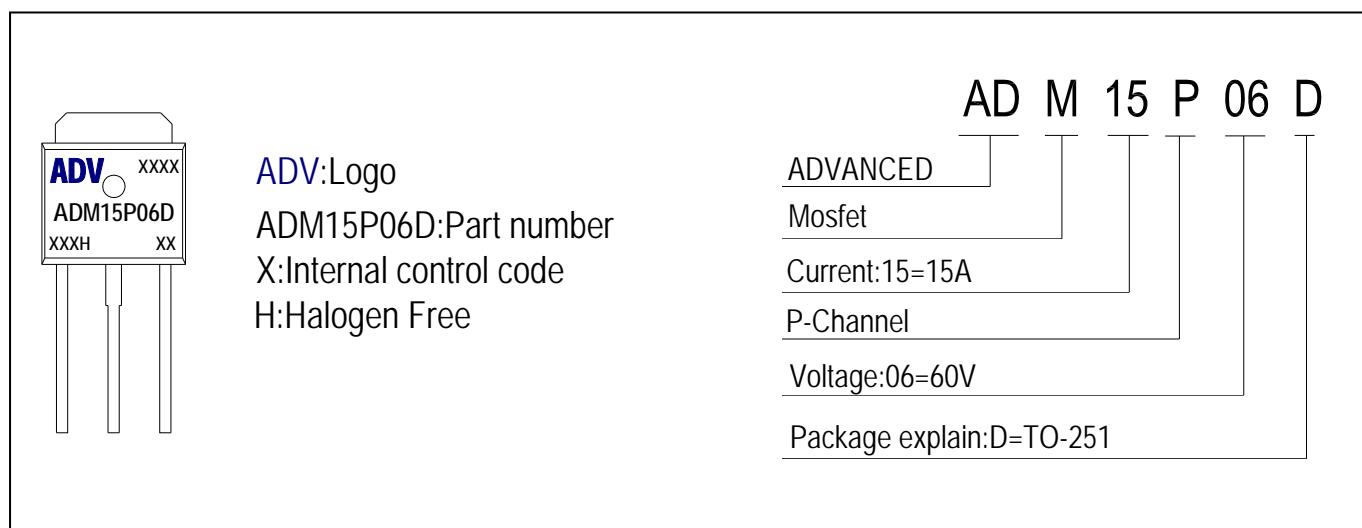
PACKAGE MECHANICAL DATA

TO-251 Package Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.200	2.400	0.087	0.094
A1	0.900	1.100	0.035	0.043
B	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.620	0.017	0.024
c1	0.480	0.620	0.019	0.024
D	6.350	6.700	0.252	0.264
D1	5.100	5.400	0.200	0.213
E	6.000	6.200	0.236	0.244
e	2.300TYP		0.091TYP	
e1	4.500	4.700	0.177	0.185
L	8.900	9.400	0.350	0.370

Making Diagram



Ordering information

Part number	Package	Marking	Packing	Quantity
ADM15P06D	TO-251	ADM15P06D	Tube	80pcs